

MASW-011087-DIE Rev. V4

#### **Features**

- Low Loss: 0.9 dB, 16 to 35 GHz
- High Isolation: 32 dB, 16 to 35 GHz
- 30 dBm CW Power Handling @ +85°C
- Switching Speed <34 ns</li>
- Integrated DC Blocks and RF Bias Networks
- Die with G-S-G RF Pads and DC Bias Pads
- RoHS\* Compliant

### **Applications**

- Test Equipment
- Radiometers
- Switching Arrays of Radar Systems
- Point-to-Point Communications
- Multi-Assembly Components

### Description

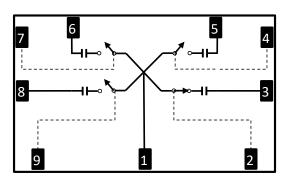
The MASW-011087 is a high power, symmetrical SP4T switch. This broadband, reflective switch was developed for Ka-Band applications that require up to 30 dBm (1 W) power handling while maintaining low insertion loss, high isolation, and fast switching speed. These switches are used in switching arrays of radars systems, radiometers, test equipment, Point-to-Point communications systems and other high frequency applications.

The SP4T MMIC utilizes MACOM's proven AlGaAs PIN diode technology. The switch is fully passivated with silicon nitride and has an added polymer layer for scratch protection. The protective coating prevents damage to the junction and the air-bridges during handling and assembly. The die has backside metallization to facilitate an epoxy die attach process.

### **Ordering Information**

Part Number	Package
MASW-011087-DIE	Die in Waffle Tray
MASW-011087-SMB	Sample Board

### **Functional Schematic**



## Pin Configuration (Backside metal is RF, DC, and thermal ground.)

Pin#	Function		
1	RF <sub>COMMON</sub>		
2	B1 (Bias 1)		
3	RF1		
4	B2 (Bias 2)		
5	RF2		
6	RF3		
7	B3 (Bias 3)		
8	RF4		
9	B4 (Bias 4)		

<sup>\*</sup> Restrictions on Hazardous Substances, compliant to current RoHS EU directive.



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## Electrical Specifications: $T_A = 25$ °C, $V_R = -10$ V, $I_{SH} = +5$ mA, $I_{SE} = +5$ mA, $Z_0 = 50$ $\Omega$

Parameter	Test Conditions	Units	Min.	Тур.	Max.
Insertion Loss (RF <sub>COMMON</sub> to RF <sub>X</sub> ON state)	20.0 GHz 28.5 GHz 35.0 GHz	dB	_	0.8 0.8 0.9	1.1
Isolation (RF <sub>COMMON</sub> to RF <sub>X</sub> OFF state)	20.0 GHz 28.5 GHz 35.0 GHz		 30 	40 34 31	_
Return Loss (RF <sub>COMMON</sub> )	20.0 GHz 28.5 GHz 35.0 GHz	dB	_	18 22 18	_
Return Loss (RF <sub>X</sub> ON state)	20.0 GHz 28.5 GHz 35.0 GHz	dB		18 22 20	_
CW Power Handling (ON state)	28.5 GHz	dBm		30	_
Switching Speed T <sub>RISE</sub> / T <sub>FALL</sub>	10% - 90% RF, 26.5 GHz	ns		10 / 18	_
Switching Speed T <sub>ON</sub> / T <sub>OFF</sub>	50% control to 90% RF, 26.5 GHz	ns	_	26 / 34	_
IIP3	27 - 32 GHz, P <sub>IN</sub> = 10 dBm, Tone Spacing 10 MHz	dBm	_	43	_
P 0.1dB	29.5 GHz	dBm		31	_

## Absolute Maximum Ratings @ +85°C1,2,3

Parameter	Absolute Maximum		
Incident Power (ON path)	30 dBm		
I <sub>SE</sub>	20 mA		
I <sub>SH</sub>	20 mA		
V <sub>R</sub>	-50 V		
Junction Temperature	+150°C		
Operating Temperature	-40°C to +85°C		
Storage Temperature	-55°C to +150°C		

- 1. Exceeding any one or combination of these limits may cause permanent damage to this device.
- MACOM does not recommend sustained operation near these survivability limits.
- Operating at nominal conditions with junction temperature less than 150°C will ensure MTTF >10<sup>6</sup> hours.

## Maximum Operation Ratings @ +25°C

Parameter	Maximum		
Incident Power (ON path)	30 dBm		
I <sub>SE</sub>	10 mA		
I <sub>SH</sub>	10 mA		
V <sub>R</sub>	-50 V		

### **Handling Procedures**

Please observe the following precautions to avoid damage:

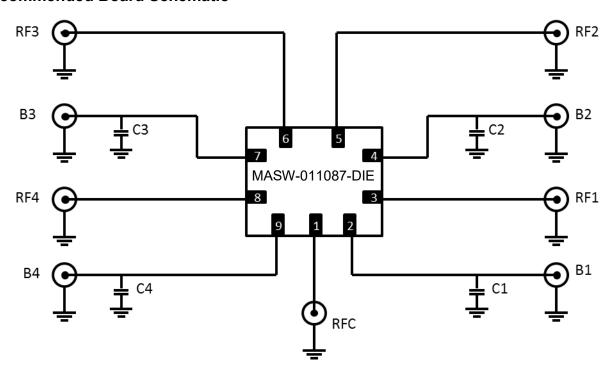
### **Static Sensitivity**

Integrated Circuits are sensitive to electrostatic discharge (ESD) and can be damaged by static electricity. Proper ESD control techniques should be used when handling these HBM class 1A devices.



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## **Recommended Board Schematic**



## **Recommended Board Component List**

Component Designator	Description	P/N
RFC, RF1, RF2, RF3, RF4	2.4 mm - Southwest Microwave connector	1492-04A-5
B1, B2, B3, B4	Johnson/Emerson RF connector Or SSMA - Southwest Microwave connector	142-0761-821 292-06A
C1, C2, C3, C4	22 pF High Frequency Capacitor	ATC600L220

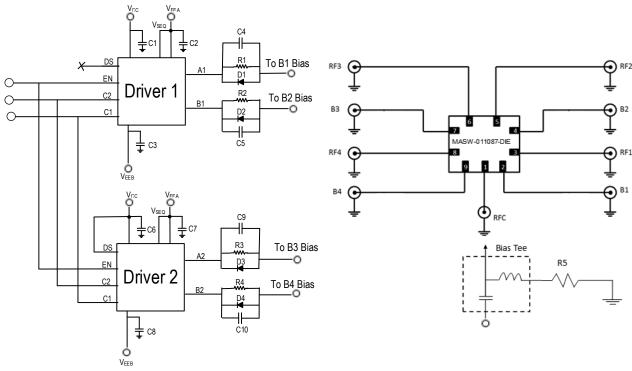
### **Truth Table**

State	B1	B2	В3	B4
RF <sub>COMMON</sub> to RF1 ON	-10 V (-5 mA)	+5 mA	+5 mA	+5 mA
RF <sub>COMMON</sub> to RF2 ON	+5 mA	-10 V (-5 mA)	+5 mA	+5 mA
RF <sub>COMMON</sub> to RF3 ON	+5 mA	+5 mA	-10 V (-5 mA)	+5 mA
RF <sub>COMMON</sub> to RF4 ON	+5 mA	+5 mA	+5 mA	-10 V (-5 mA)



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### MADR-011022 Driver with MASW-011087 Switch Application Schematic



### **Parts List**

Part	Value
C1,C3,C6,C8	0.1 μF
C2,C7	47 pF
C4,C5,C9,C10	470 pF
R1 - R4	650 Ω
R5	1.2 ΚΩ
D1 - D4	1N4148WS

## To calculate off-chip bias resistors:

R5 = 
$$(|V_{EEB}| - 2.64 \text{ V} - 0.7 \text{ V} - 0.4 \text{ V}) / I_{SE})$$
  
R1 - 4 =  $(V_{CC} - 1.32 \text{ V} - 0.4 \text{ V}) / (I_{SH})$ 

For example, with  $V_{CC}$  = +5 V and  $V_{EEB}$  = -10 V:

Voltage drop of D1 - D4 is 0.7 V and voltage drop at driver output is 0.4 V.

## Switch Minimum Reverse DC Voltage<sup>4</sup>

Frequency (GHz)	Minimum Reverse DC Voltage at B1 - B4		
14	-6.5		
20	-5		
25	-4		
30	-4		
35	-4		
38	-4		

4. Calculated minimum reverse bias voltage to maintain low loss under 1 W of incident power with 1.5:1 VSWR. R. Caverly and G. Hiller, "Establishing the Minimum Reverse Bias for a P-I-N Diode in a High Power Switch," IEEE Transactions on Microwave Theory and Techniques, Vol.38, No.12, December 1990.



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## **MADR-011022 Driver with Switch Logic Table**

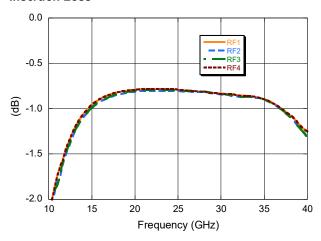
	Inputs		Outputs			RF OUTPUT	
EN	C2	C1	A1	B1	A2	B2	
1	X	Х	Н	Н	Н	Н	ALL OFF
0	0	0	L	Н	Н	Н	RF1 - ON
0	0	1	Н	L	Н	Н	RF2 - ON
0	1	0	Н	Н	L	Н	RF3 - ON
0	1	1	Н	Н	Н	L	RF4 - ON



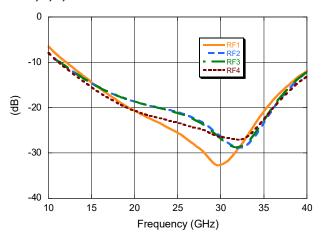
## MASW-011087-DIE

## **Typical Performance Curves**

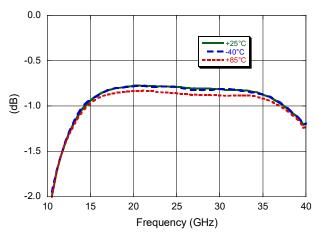
#### Insertion Loss



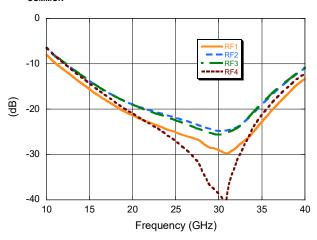
#### RF 1, 2, 3, 4 Return Loss in On State



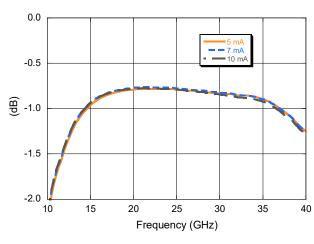
### Insertion Loss over Temperature



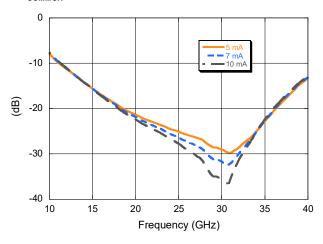
RF<sub>COMMON</sub> Return Loss in ON State



#### Insertion Loss over Bias Current



RF<sub>COMMON</sub> Return Loss in ON State over Bias Current

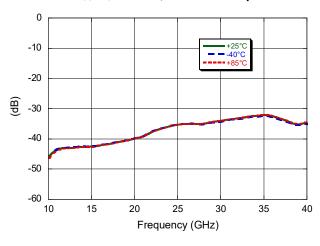




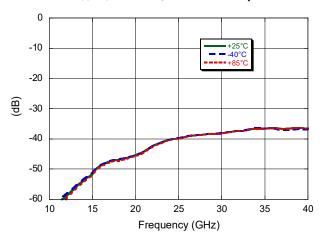
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### **Typical Performance Curves**

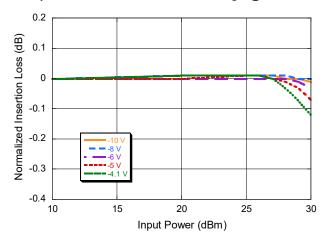
### Isolation RF<sub>COMMON</sub> to RF2, RF3 over Temperature



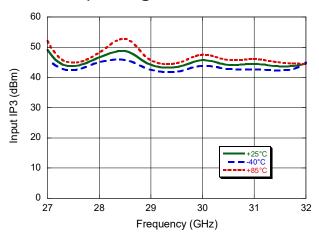
### Isolation RF<sub>COMMON</sub> to RF1, RF4 over Temperature



#### Compression over Reverse-Bias Voltage @ 29.5 GHz



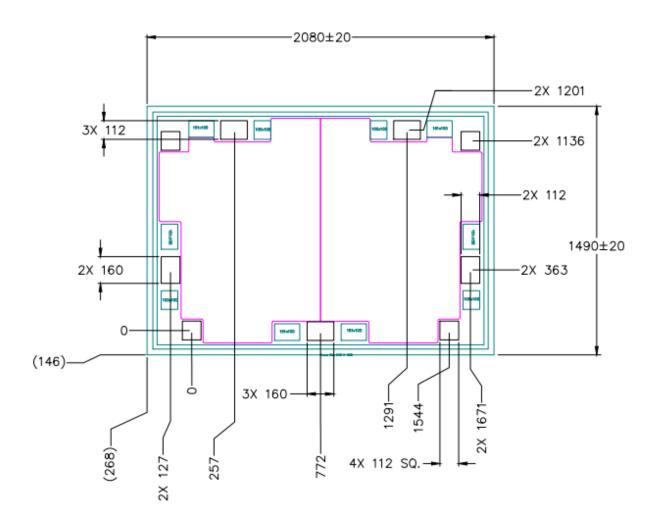
#### IIP3 over Temperature @ 5 V / 5 mA





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### **Outline Drawing**



### NOTES:

- UNLESS OTHERWISE SPECIFIED, ALL DIMENSIONS SHOWN AS um WITH A TOLERANCE OF ±5um.
- 2. DIE THICKNESS IS 100 ±12.5um



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